## HYBRID SOLID STATE RELAY



#### Features:

- High Voltage/Low Resistance
- Single Pole, Single Throw Available in Form A or Form B
- Wide Band Gap Semiconductors for low Resistance
- No SEE LET>82 MeV\*cm<sup>2</sup>/mg
- 100K + Rad Hard TID 100 kRads (S and SE Grades)
- TID 45 Krads (L and LE grades)
- Magnetically Coupled Command for fast response
- · No Optocoupler, no optocoupler issues
- Selectable Continuous or Mag Latch Function
- Logic Level Drive
- Rugged Hermetic Package

### Specifications:

Bias Input Voltage 4.7 to 5.3 VDC

Bias input current 100 mA typical, 200 mA maximum

Command input 1 mA compatible with TTL logic levels

Input/output and all pins to case isolation 1kV
Power Dissipation 10 watts at maximum rated
case temperature

Case temperature range:

Operating -55°C to +85°C (L or S grades) Operating -55°C to +125°C (LE or SE ades)

Operating 0° to +55°C (EU Grade) Storage -65°C to +150°C

Weight 32 grams typical

For continuous operation, connect, 5 VDC bias from pin 1, to bias ground pin 2.

Ground pin 3 and apply +5 VDC to pin 5 pin to energize the SSR.

For latch operation, leave pin 3 open, connect +5 VDC bias from pin 1 to bias ground pin 2.

To energize apply +5 VDC pulse, 25 microseconds minimum to pin 5.

To de-energize apply +5 VDC pulse, 25 microseconds minimum to pin 4.

Power Dissipation:

Total steady state power dissipation of the model 53802 and 53803 is limited to 10 watts provided the baseplate temperature is limited to the rated temperature.



Modular Devices, Inc.

Power Conversion for Space and Military/Aerospace

## MODELS 53802/53803

Model 53802 is a SPST form B (normally closed when de-energized) SSR Model 53803 is a SPST form A (normally open when de-energized) SSR.

Both types use Wide Bandgap power semiconductors for high performance, are magnetically coupled and can be user configured for continuous or pulse latching.

Wide band gap (WBG) semiconductors, such as GaN (Gallium Nitride) and SiC (Silicon Carbide) provide an order of magnitude improvement in SSR voltage drop compared to SSRs using Silicon based power devices.

Also, WBG semiconductors of a given dimension can withstand higher electric fields than Silicon semiconductors, the physical dimensions of these WBG parts are considerably smaller than their Silicon competitors. The result of WBG is much lower channel resistances and reduced drive requirements.

Many SSR manufacturers drive their SSR power device with opto couplers consisting of an LED emitter driving a multi-diode photo-voltaic stack.

Both the LED's and photovoltaic stacks are challenged by radiation environments. A second disadvantage of opto coupled drive is slow turn on and turn off response.

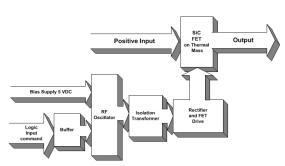
MDI replaces the optocoupler function with a tiny, transformer isolated RF drive signal. This solves the opto coupler problems and gives faster, more temperature stable operation, as well as excellent radiation resistance.

Latching configuration

Some electromechanical relays have a magnetic latching function. The relay armature has two stable states and two relay coils. A short pulse on one of the coils causes the relay to change state. The last selected state persists even after power is removed.

The magnetically isolated SSR can have a somewhat similar mag latch function in that it can be energized either by a continuous signal, or by a short duration pulse. However, unlike an electromechanical relay, after removal of bias power the DC SSR reverts back to its initial state.

The MDI DC SSR can be user configured to the latching function by connecting a jumper or leaving the jumper open for continuous operation.



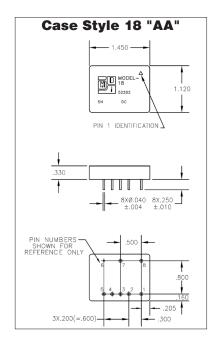
600V/20A Solid State Relay Model 53802 Form B Model 53803 Form A

PARAMETER	CONDITION	MIN	TYP	MAX	
Contact Ratng V	Max	_	_	600V	
Contact Rating I	Max	_	_	20A	
Contact Resistance, 25°C	Energized	_	$0.075 \Omega$	0.1 Ω	
Contact Resistance, 125°C	Energized	_	0.15 Ω	0.2 Ω	
Leakage Current, 600V, 25°C	Off	_	_	60µA	
Leakage Current, 600V, 125°C	Off	_	_	100μΑ	
Bias Voltage	_	4.7	5.0	5.3V	
Bias Current	_	_	100	200mA	
Command/Pulse Inputs on	_	3.0	5.0	6.0V	
Command/Pulse Inputs off	_	0	0.5	1.0V	
Command Current	_	0.1	0.8	2.0mA	
Delay Time, energized	_	_	30	75µS	
Delay Time, de-energized	_	_	20	60µS	
Energize Time, dynamic	_	_	12	30µS	
De-energize time, dynamic	_	_	5	20μS	
Latch/Unlatch Pulse Width	Minimum	25µS	_		

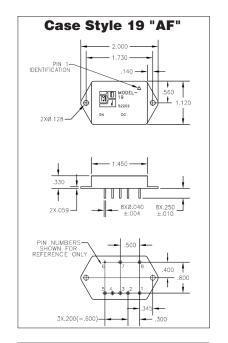
For Heat Removal and Mounting Recommendations See MDI application notes on mounting considerations for DC-DC Converters

# 53802/53803

### HYBRID SOLID STATE RELAY



Pin Ou	t Chart
Pin 1	Bias +5 VDC
Pin 2	Bias Gnd
Pin 3	Latch/No Latch
Pin 4	Pulse Off
Pin 5	Pulse On
Pin 6	Case
Pin 7	Switch Positive
Pin 8	Switch Negative



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Pin 1	Bias +5 VDC
Pin 2	Bias Gnd
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Pin 4	Pulse Off
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Model No. Case Style	Pin Count	Mounting
53802/53803 - 18 AA	8	Seam Weld Flangeless PCB Mount
53802/53803 - 19 AF	8	Seam Weld PCB Mount with Flance

### GRADE LEVELS:

Please specify grade level for your application. EU grade units will be shipped if no option is specified.

EU Engineering Units

45K, +85°C aerospace

S 100K+™, +85°C space SE 100K+™, +100K™, +125°C space LE 45K +85°C aerospace

